

“ Customers don’t come to us to be sold. They come to us for solutions for their interconnect problems. ”

Bill Miller, ISI President & CEO

IC Obsolescence Adapter

Concept & Feasibility

Design

Prototype & Qualification

Bare Die Assembly

Advanced SMT

Module Interconnect

Module Packaging

Test

Challenge:

Major Telecom Customer received End-Of-Life notification on an ASIC vital to 9 different systems. A compact, cost effective and reliable solution, maintaining the existing footprint, SONET and EVT specs and be “debuggable”, was all required within a very tight time frame.



Solution:

An FPGA based adapter was designed to replace the obsolete ASIC. A custom FlexFrame™ interconnect on the bottom was designed to match the QFP footprint and allow for component placement on the bottom of the adapter. ISI designed the adapter PCB and FlexFrame in 5 days and shipped prototypes in 10 days. Product is now in volume production of several thousand pieces per month.